

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yang Hong Heng</td> <td>01/26/2008</td> </tr> <tr> <td>Kean Cheong Lee</td> <td>01/29/2008</td> </tr> <tr> <td>Xaver Schloegel</td> <td>01/15/2008</td> </tr> <tr> <td>Gerhard Deml</td> <td>01/16/2008</td> </tr> <tr> <td>Ralf Otremba</td> <td>01/16/2008</td> </tr> <tr> <td>Juergen Schredl</td> <td>01/15/2008</td> </tr> </tbody> </table>		Name	Execution Date	Yang Hong Heng	01/26/2008	Kean Cheong Lee	01/29/2008	Xaver Schloegel	01/15/2008	Gerhard Deml	01/16/2008	Ralf Otremba	01/16/2008	Juergen Schredl	01/15/2008
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Ralf Otremba	01/16/2008														
Juergen Schredl	01/15/2008														
RECEIVING PARTY DATA															
Name:	Infineon Technologies AG														
Street Address:	Am Campeon 1-12														
City:	Neubiberg														
State/Country:	GERMANY														
Postal Code:	85579														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11995242</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11995242										
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Application Number:	11995242														
CORRESPONDENCE DATA															
Fax Number:	(612)573-2005														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
Phone:	612-573-2000														
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Correspondent Name:	Mark L. Gleason														
Address Line 1:	Fifth St. Towers, 100 South Fifth St.														
Address Line 2:	Suite 2250														
Address Line 4:	Minneapolis, MINNESOTA 55402														
ATTORNEY DOCKET NUMBER:	I431.231.101														

CH \$40.00 11995242

NAME OF SUBMITTER:

Mark L. Gleason

Total Attachments: 3

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ASSIGNMENT

For good and valuable consideration, I, Yang Hong Heng, a citizen of Malaysia, residing at 162, Jalan Mawar 8, Taman Mawar, Muar Johor, Malaysia, Kean Cheong Lee, a citizen of Malaysia, residing at 20 Jln Saujan 2/12 Tmn, Saujana Sek 2 Bkt Katil, Melaka, Malaysia, Xaver Schloegel, a citizen of Germany, residing at Raiffeisenstr. 22, Sachsenkam, Germany, Gerhard Deml, a citizen of Germany, residing at Fred-Hartmann-Weg 11, Erding, Germany, Ralf Otremba, a citizen of Germany, residing at Ahornstr. 42, Kaufbeuren, Germany and Juergen Schredl, a citizen of Germany, residing at Lavendelweg 1, Mering, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at Am Campeon 1-12, Neubiberg, Germany, 85579, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on January 10, 2008

US. Serial No. 11/995,242.

entitled: SEMICONDUCTOR MODULE FOR A SWITCHED-MODE POWER SUPPLY AND METHOD FOR ITS ASSEMBLY

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements on the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: Yang Hong Heng DATE: 26/JAN/2008
NAME: Yang Hong Heng

SIGNATURE: _____ DATE: _____
NAME: Kean Cheong Lee

ASSIGNMENT

For good and valuable consideration, I, Yang Hong Heng, a citizen of Malaysia, residing at 162, Jalan Mawar 8, Taman Mawar, Muar Johor, Malaysia, Kean Cheong Lee, a citizen of Malaysia, residing at 20 Jln Saujan 2/12 Tmn, Saujana Sck 2 Bkt Katil, Melaka, Malaysia, Xaver Schloegel, a citizen of Germany, residing at Raiffeisenstr. 22, Sachsenkam, Germany, Gerhard Deml, a citizen of Germany, residing at Fred-Hartmann-Weg 11, Erding, Germany, Ralf Otremba, a citizen of Germany, residing at Ahornstr. 42, Kaufbeuren, Germany and Juergen Schredl, a citizen of Germany, residing at Lavendelweg 1, Mering, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at Am Campeon 1-12, Neubiberg, Germany, 85579, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

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Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

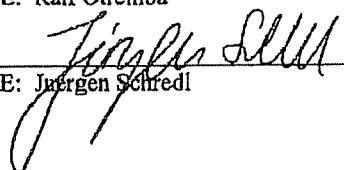
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SIGNATURE: _____ DATE: _____
NAME: Yang Hong Heng
SIGNATURE:  _____ DATE: 29-1-2008
NAME: Kean Cheong Lee

SIGNATURE:  DATE: 15.01.08
NAME: Xavier Schloegel

SIGNATURE:  DATE: 16.01.08
NAME: Gerhard Deml

SIGNATURE:  DATE: 16.01.2008
NAME: Ralf Otremba

SIGNATURE:  DATE: 2008/01/15
NAME: Juergen Schredl